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Finetech's Sigma Bonder Selected for Canada's National Optics Institute

GILBERT, AZ and Quebec City, Canada (January 18, 2017) - [Finetech](#), a global supplier of micro-assembly equipment, and the [National Optics Institute](#) (INO), Canada's largest center of expertise in optics and photonics, announce the addition of a FINEPLACER® Sigma bonding system at INO's micro-opto-electromechanical systems facility. The semi-automatic die bonder will be used by researchers and developers specializing in micro-electromechanical systems (MEMS) and MOEMS.

Over the past 20 years, INO has been developing an expertise in packaging of MOEMS and integrated optics. INO's packaging solutions are used in several industries, including space industry, telecommunications, biomedical, natural resources, defense and security. "The addition of Finetech's high-accuracy flip chip bonder to INO's current toolkit will enhance its current offering for many types of heterogeneous integration and photonic advanced packaging. Thanks to the state-of-the art precision placement and the significant versatility of the system, this will be an essential tool to meet many custom assemblies required by our various clients", says Bruno Fisette, Research Scientist MOEMS.

The [FINEPLACER® Sigma](#) is ideally suited for high-density array applications and high bond force (up to 1000N) requirements, coupled with Finetech's renowned sub-micron placement accuracy. The system is the perfect choice for a wide variety of Wafer Level Packaging (FOWLP, W2W, C2W) with high bump count used to assemble MEMS/MOEMS, IR/ image sensors, focal plane arrays, and high power device packaging. This includes assembly of complex 2.5D and 3D IC packages. The FPXvision™ vision alignment system provides the highest resolution at all magnification levels and real-time optimized camera images. It enables the smallest devices and features to be clearly observed across the entire field of view, even with large components and substrates.



About Finetech

Finetech is a leading manufacturer of equipment for manual and fully automatic high-precision bonding and component rework. The company services customers in a broad range of industries including aerospace, medical technology, consumer electronics, semiconductor, optoelectronics, military, universities and research. Corporate headquarters and main production are in Berlin, Germany. Sales and Technical Support Centers are located in Gilbert, Arizona; Manchester, New Hampshire; Shanghai, China; Kuala Lumpur, Malaysia; and Toyko, Japan. www.finetechusa.com

About INO

A leading technology designer and developer, INO is Canada's largest center for industrial optics and photonics expertise. It is an international leader in its field, having developed over 6,000 custom solutions to date for Quebec and Canadian companies across a wide variety of fields. INO has performed 64 technology transfers and helped create 30 spinoff companies employing over 1,000 people. INO has 194 employees, more than 80% of whom are scientists involved in research. The activities of INO are made possible through the support of the ministère de l'Économie, de la Science et de l'Innovation and Canada Economic Development for Quebec Regions. www.ino.ca

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